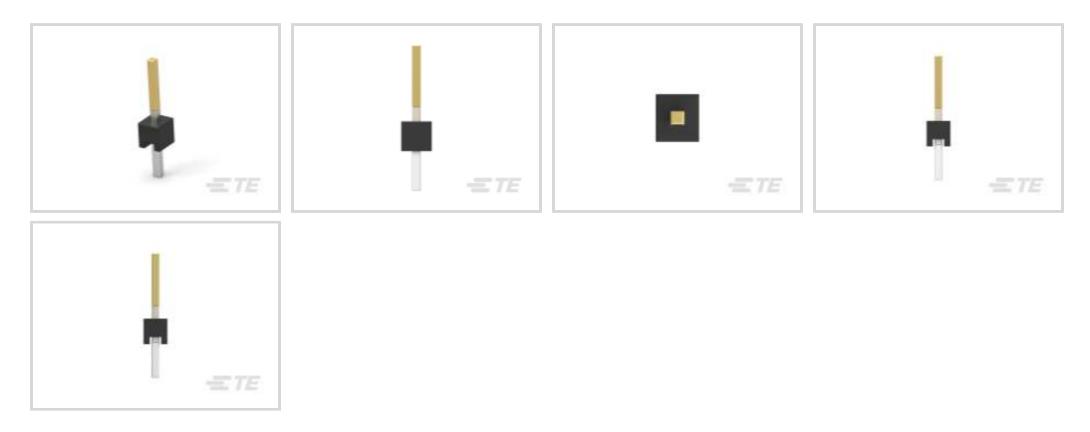


## AMPMODU | AMPMODU Headers

TE Internal #: 5-146280-1 PCB Mount Header, Vertical, Board-to-Board, 1 Position, 2.54 mm [. 1 in] Centerline, Breakaway, Gold, Through Hole - Solder, Signal, AMPMODU Headers

### View on TE.com >

#### Connectors > PCB Connectors > PCB Headers & Receptacles



PCB Connector Assembly Type: PCB Mount Header

PCB Mount Orientation: Vertical

Connector System: Board-to-Board

Number of Positions: 1

Number of Rows: 1

## Features

**E** 

## **Product Type Features**

PCB Connector Assembly Type	PCB Mount Header
Connector System	Board-to-Board
Header Type	Breakaway
Sealable	No
Connector & Contact Terminates To	Printed Circuit Board
Configuration Features	
Connector Contact Load Condition	Fully Loaded
PCB Mount Orientation	Vertical
Number of Positions	1
Number of Rows	1
Board-to-Board Configuration	Parallel
Body Features	
Primary Product Color	Black
Contact Features	

PCB Mount Header, Vertical, Board-to-Board, 1 Position, 2.54 mm [.1 in] Centerline, Breakaway, Gold, Through Hole - Solder, Signal, AMPMODU Headers



Mating Square Post Dimension	.64 mm[.025 in]
	100 – 200 µin
PCB Contact Termination Area Plating Material Finish	Matte
Contact Shape & Form	Square
Contact Underplating Material	Nickel
PCB Contact Termination Area Plating Material	Tin-Lead
Contact Base Material	Copper Alloy
Contact Mating Area Plating Material	Gold
Contact Mating Area Plating Material Thickness	.381 μm[15 μin]
Contact Type	Pin
Contact Current Rating (Max)	3 A
Termination Features	
Square Termination Post & Tail Dimension	.64 mm[.025 in]
Termination Post & Tail Length	3.05 mm[.12 in]
Termination Method to Printed Circuit Board	Through Hole - Solder
Mechanical Attachment	
PCB Mount Retention Type	Solder Tail

Mating Alignment	Without
PCB Mount Retention	Without
PCB Mount Alignment	Without
Connector Mounting Type	Board Mount
Housing Features	
Centerline (Pitch)	2.54 mm[.1 in]
Housing Material	LCP (Liquid Crystal Polymer), LCP-GF (Liquid Crystal Polymer)
Dimensions	
PCB Thickness (Recommended)	1.6 mm[.063 in]
Usage Conditions	
Housing Temperature Rating	High
Operating Temperature Range	-65 – 105 °C[-85 – 221 °F]
Operation/Application	
Circuit Application	Signal

**C** For support call+1 800 522 6752

PCB Mount Header, Vertical, Board-to-Board, 1 Position, 2.54 mm [.1 in] Centerline, Breakaway, Gold, Through Hole - Solder, Signal, AMPMODU Headers



## **Industry Standards**

Approved Standards	CSA LR7189, UL E28476
UL Flammability Rating	UL 94V-0
Packaging Features	
Packaging Quantity	520
Packaging Type	Carton
<b>Product Compliance</b> For compliance documentation, visit the product page on TE.com>	

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2023 (235) Candidate List Declared Against: JAN 2023 (233) Does not contain REACH SVHC
Halogen Content	Low Bromine/Chlorine - Br and Cl < 900 ppm per homogenous material. Also BFR /CFR/PVC Free

### Pin-in-Paste capable to 260°C

#### Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

# **Compatible Parts**

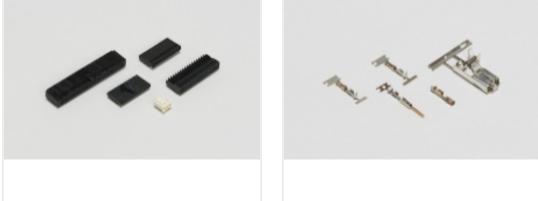
PCB Mount Header, Vertical, Board-to-Board, 1 Position, 2.54 mm [.1 in] Centerline, Breakaway, Gold, Through Hole - Solder, Signal, AMPMODU Headers





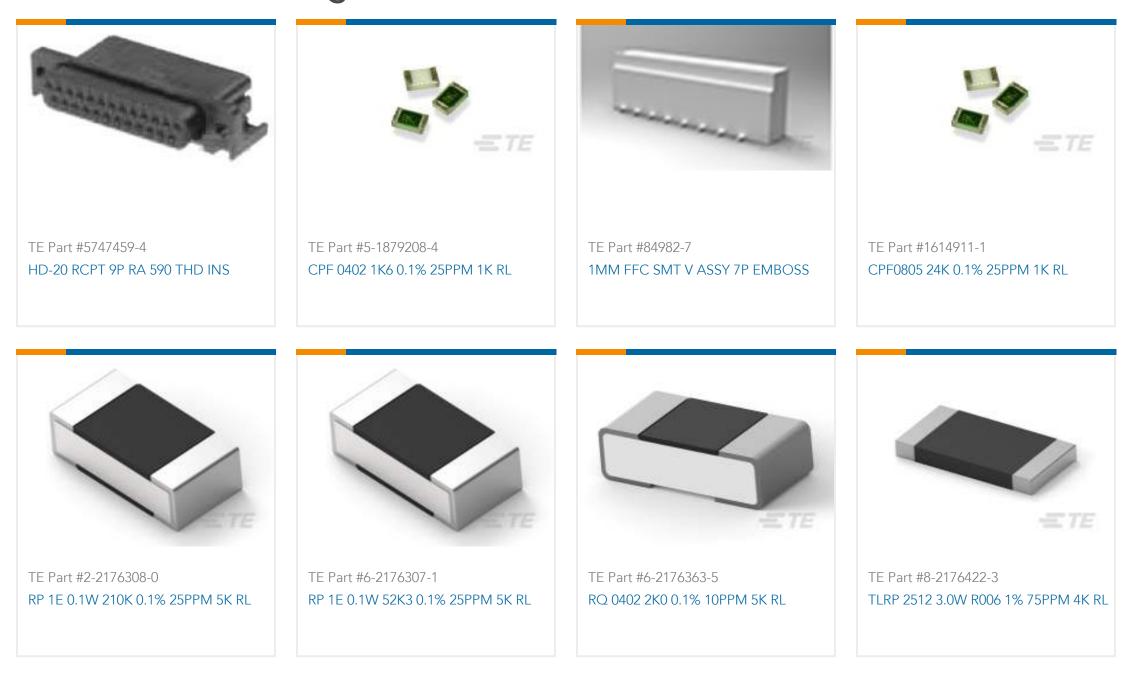
# Also in the Series AMPMODU Headers





Wire-to-Board Connector Assemblies	Wire-to-Board Connector Contacts(65)
& Housings(5)	

# Customers Also Bought



PCB Mount Header, Vertical, Board-to-Board, 1 Position, 2.54 mm [.1 in] Centerline, Breakaway, Gold, Through Hole - Solder, Signal, AMPMODU Headers



TE Part #1462041-8 IMB03CTS=IM RELAY 140mW 5V HDV

# Documents

# **CAD** Files

3D PDF

3D

**Customer View Model** 

ENG\_CVM\_CVM\_5-146280-1\_D.2d\_dxf.zip

English

Customer View Model ENG\_CVM\_CVM\_5-146280-1\_D.3d\_igs.zip

English

**Customer View Model** 

ENG\_CVM\_CVM\_5-146280-1\_D.3d\_stp.zip

English

By downloading the CAD file I accept and agree to the Terms and Conditions of use

## Datasheets & Catalog Pages AMPMODU\_INTERCONNECTION\_SYSTEM\_SECTION5

English

Product Environmental Compliance MD\_5-146280-1\_04252018514\_dmtec

English

MD\_5-146280-1\_04252018514\_dmtec

English